

## Product Summary

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	Package	I <sub>D</sub> T <sub>A</sub> = +25°C
-20V	52mΩ @V <sub>GS</sub> = -4.5V	SOT23	-5.0A
	100mΩ @V <sub>GS</sub> = -2.5V		-3.6A

## Description

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

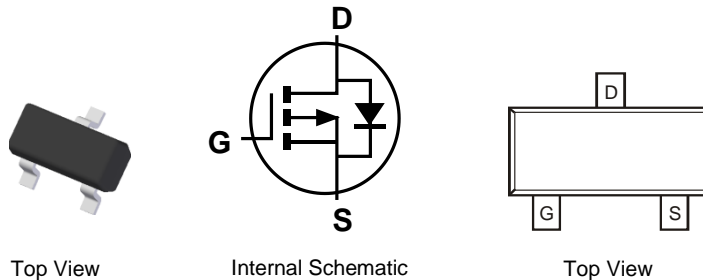
- Backlighting
- Power Management Functions
- DC-DC Converters
- Motor Control

## Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **An Automotive-Compliant Part is Available Under Separate Datasheet ([DMG2305UXQ](#))**

## Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Terminals Connections: See Diagram Below
- Weight: 0.009 grams (Approximate)

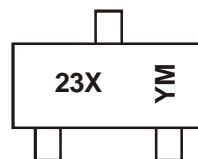


## Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DMG2305UX-7	Standard	SOT23	3,000/Tape & Reel
DMG2305UX-13	Standard	SOT23	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



23X = Product Type Marking Code  
 YM = Date Code Marking  
 Y or Y= Year (ex: D = 2016)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2009	~	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026
Code	W	~	D	E	F	G	H	I	J	K	L	M	N

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	-20	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-4.2 -3.3	A
	t < 10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-5.0 -4.0	A
Pulsed Drain Current (Note 6)			I <sub>DM</sub>	-10	A

**Thermal Characteristics**

Characteristic			Symbol	Value	Unit
Power Dissipation (Note 5)			P <sub>D</sub>	1.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		R <sub>θJA</sub>	90	°C/W
	t < 10s			64	°C/W
Thermal Resistance, Junction to Case (Note 7)			R <sub>θJC</sub>	33	°C/W
Operating and Storage Temperature Range			T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b> (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	-1.0	μA	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±8V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b> (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.5	—	-0.9	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	40	52	mΩ	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4.2A
			52	100		
			68	200		
						V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -2A
Forward Transfer Admittance	Y <sub>FS</sub>	—	9	—	s	V <sub>DS</sub> = -5V, I <sub>D</sub> = -4A
<b>DYNAMIC CHARACTERISTICS</b> (Note 8)						
Input Capacitance	C <sub>ISS</sub>	—	808	—	pF	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V f = 1.0MHz
Output Capacitance	C <sub>OSS</sub>	—	85	—	pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>	—	77	—	pF	
Gate Resistance	R <sub>g</sub>	—	15.2	—	Ω	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1.0MHz
<b>SWITCHING CHARACTERISTICS</b> (Note 8)						
Total Gate Charge	Q <sub>g</sub>	—	10.2	—	nC	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -4V, I <sub>D</sub> = -3.5A
Gate-Source Charge	Q <sub>gs</sub>	—	1.3	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	2.2	—	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	—	10.8	—	ns	V <sub>DS</sub> = -4V, V <sub>GS</sub> = -4.5V, R <sub>g</sub> = 6Ω, I <sub>D</sub> = -1A
Turn-On Rise Time	t <sub>R</sub>	—	13.7	—	ns	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	—	79.3	—	ns	
Turn-Off Fall Time	t <sub>F</sub>	—	34.7	—	ns	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.
  - Repetitive rating, pulse width limited by junction temperature.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to product testing.

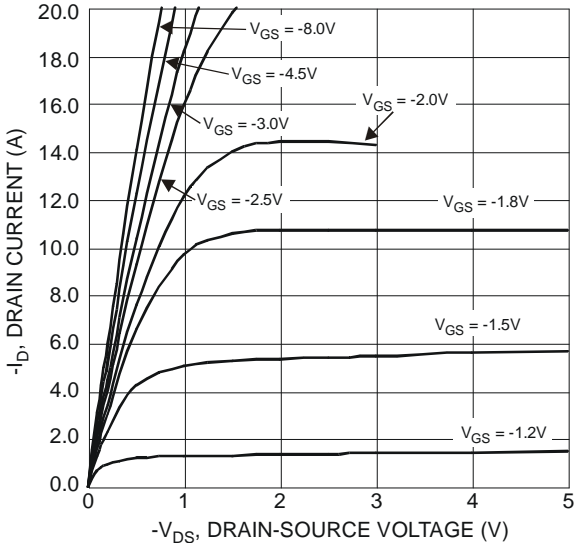


Figure 1 Typical Output Characteristics

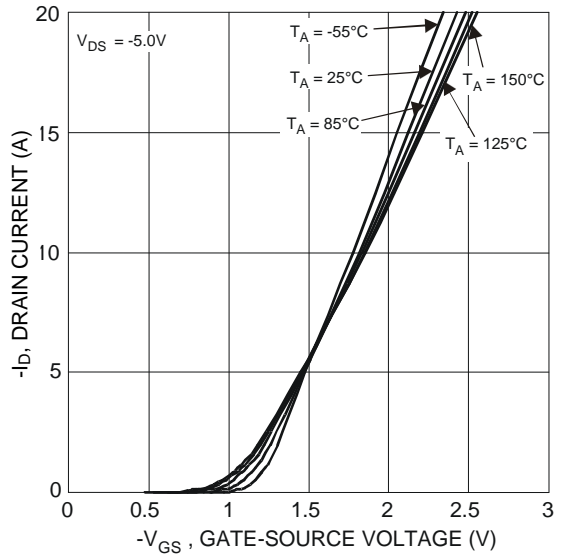


Figure 2 Typical Transfer Characteristics

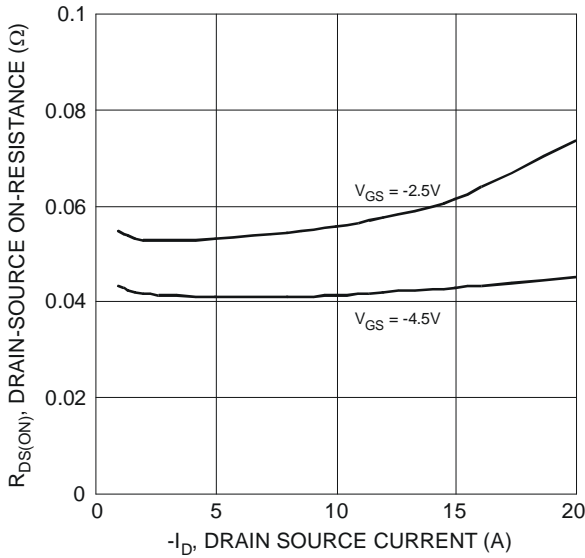


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

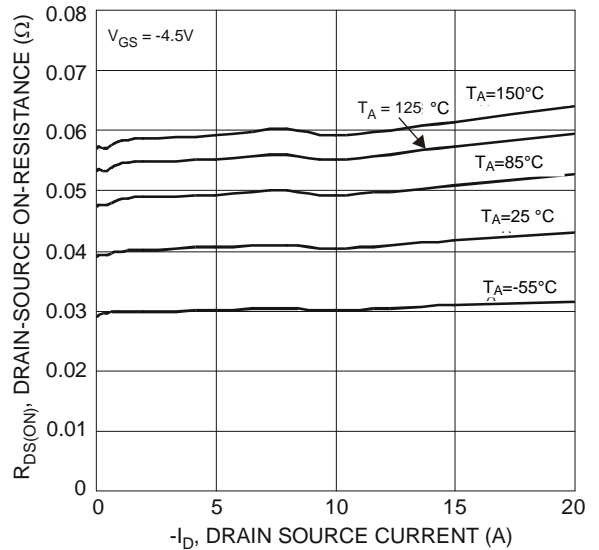


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

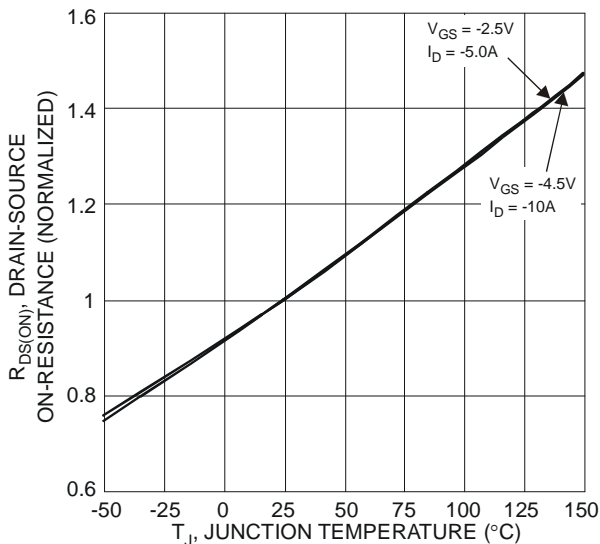


Figure 5 On-Resistance Variation with Temperature

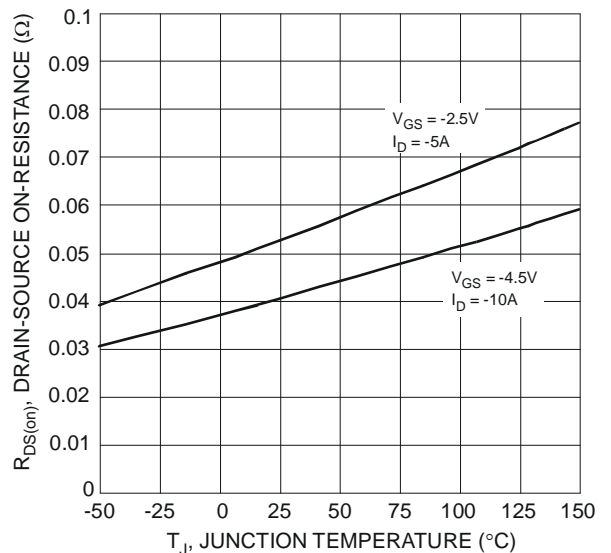


Figure 6 On-Resistance Variation with Temperature

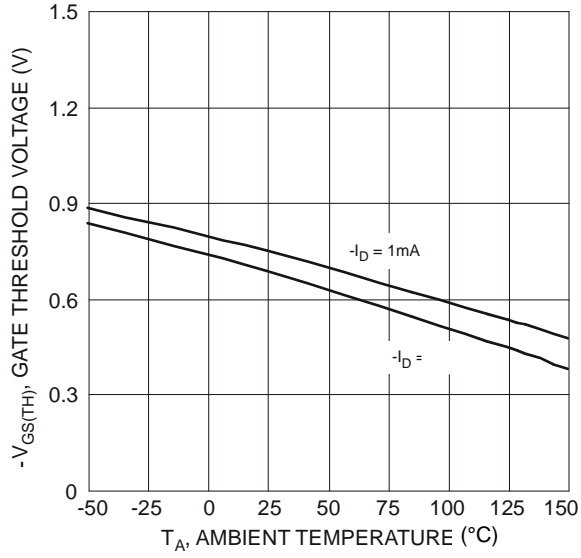


Figure 7 Gate Threshold Variation vs. Ambient Temperature

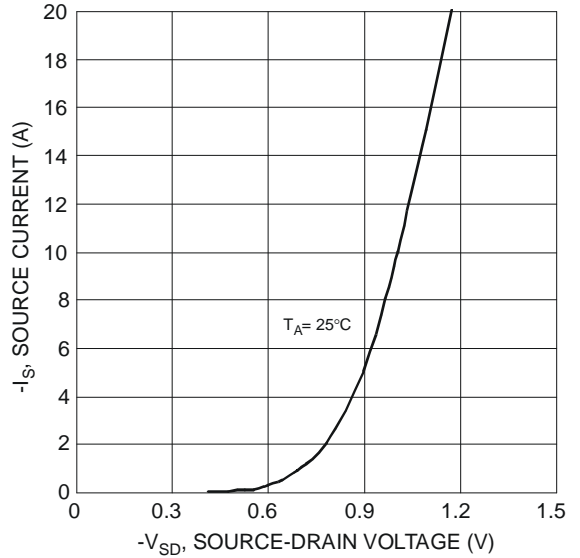
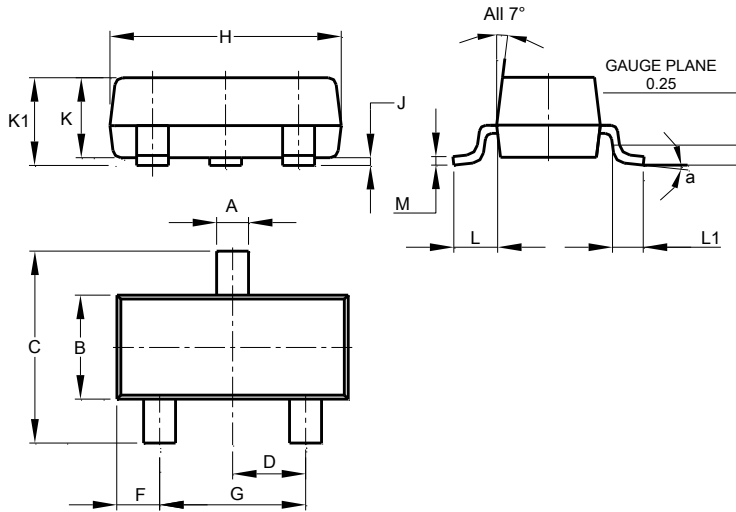


Figure 8 Diode Forward Voltage vs. Current

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**

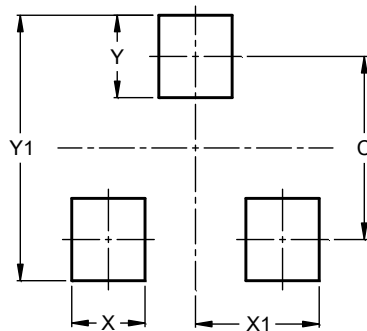


SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	-
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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